

# PHD/PHU77NQ03T

N-channel TrenchMOS FET

Rev. 01 — 28 November 2006

Product data sheet

## 1. Product profile

### 1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology.

### 1.2 Features

- Fast switching
- Low thermal resistance

### 1.3 Applications

- DC-to-DC converters
- Computer motherboard

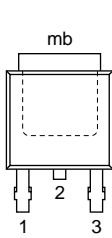
### 1.4 Quick reference data

- $V_{DS} \leq 25\text{ V}$
- $I_D \leq 75\text{ A}$
- $R_{DSon} \leq 9.5\text{ m}\Omega$
- $Q_{GD} = 3.2\text{ nC (typ)}$

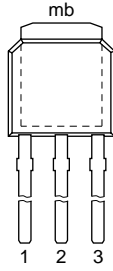
## 2. Pinning information

Table 1. Pinning

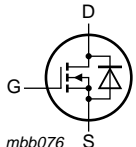
Pin	Description	Simplified outline	Symbol
1	gate (G)		
2	drain (D) <a href="#">[1]</a>		
3	source (S)		
mb	mounting base; connected to drain (D)		



SOT428 (DPAK)



SOT533 (IPAK)



mbb076

[1] It is not possible to make a connection to pin 2 of the SOT428 package.

### 3. Ordering information

**Table 2. Ordering information**

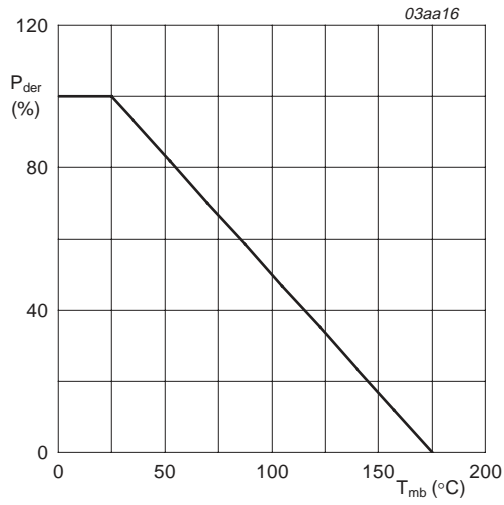
Type number	Package		Version
	Name	Description	
PHD77NQ03T	DPAK	plastic single-ended surface-mounted package; 3 leads (one lead cropped)	SOT428
PHU77NQ03T	IPAK	plastic single-ended package; 3 leads (in-line)	SOT533

### 4. Limiting values

**Table 3. Limiting values**

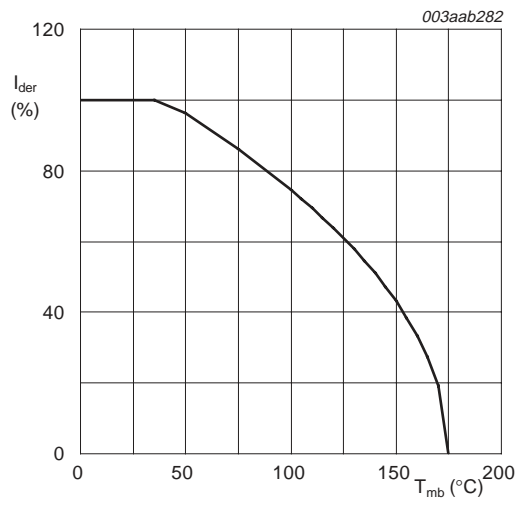
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	25	V
$V_{DGR}$	drain-gate voltage (DC)	$25\text{ °C} \leq T_j \leq 175\text{ °C}$ ; $R_{GS} = 20\text{ k}\Omega$	-	25	V
$V_{GS}$	gate-source voltage		-	$\pm 20$	V
$I_D$	drain current	$T_{mb} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; see <a href="#">Figure 2</a> and <a href="#">3</a>	-	75	A
		$T_{mb} = 100\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; see <a href="#">Figure 2</a>	-	55.9	A
$I_{DM}$	peak drain current	$T_{mb} = 25\text{ °C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; see <a href="#">Figure 3</a>	-	240	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 1</a>	-	107	W
$T_{stg}$	storage temperature		-55	+175	°C
$T_j$	junction temperature		-55	+175	°C
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$	-	75	A
$I_{SM}$	peak source current	$T_{mb} = 25\text{ °C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	-	240	A
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	unclamped inductive load; $I_D = 32\text{ A}$ ; $t_p = 0.17\text{ ms}$ ; $V_{DS} \leq 25\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; starting at $T_j = 25\text{ °C}$	-	100	mJ



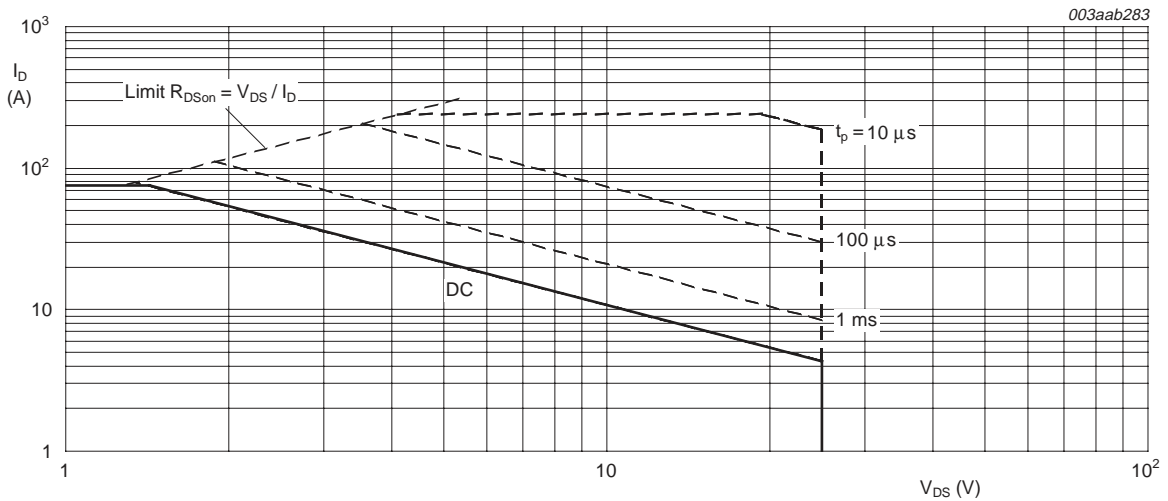
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of mounting base temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature



T<sub>mb</sub> = 25 °C; I<sub>DM</sub> is single pulse

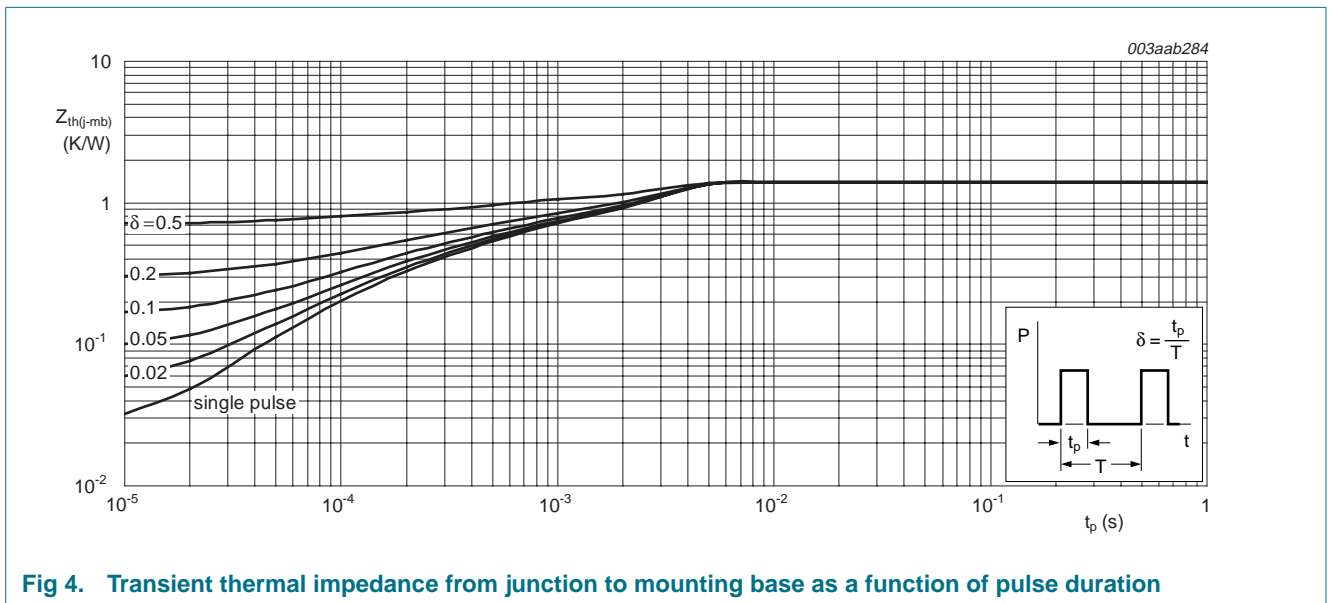
Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

### 5. Thermal characteristics

**Table 4. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see <a href="#">Figure 4</a>	-	-	1.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	minimum footprint	[1] -	75	-	K/W
		SOT404 minimum footprint	[1] -	50	-	K/W
		SOT533	vertical in free air	-	70	-

[1] Mounted on a printed-circuit board; vertical in still air.



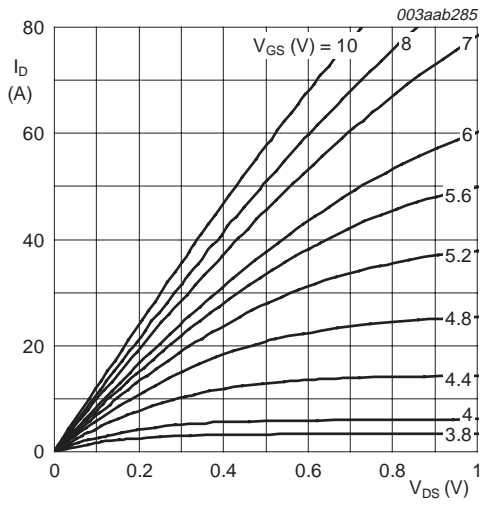
**Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration**

## 6. Characteristics

**Table 5. Characteristics**

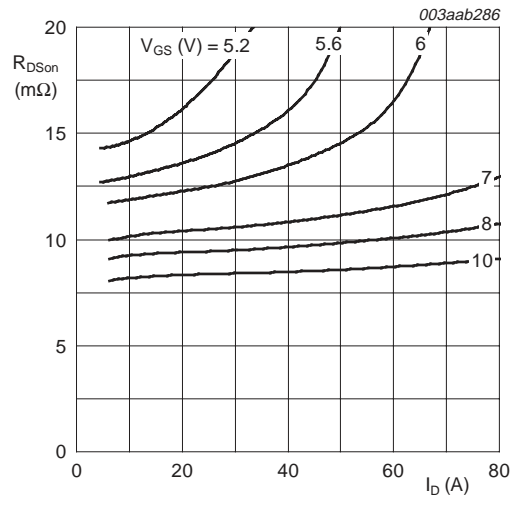
$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}; V_{GS} = 0\ \text{V}$				
		$T_j = 25\text{ °C}$	25	-	-	V
		$T_j = -55\text{ °C}$	25	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ \text{mA}; V_{DS} = V_{GS}$ ; see <a href="#">Figure 9</a> and <a href="#">10</a>				
		$T_j = 25\text{ °C}$	2.1	2.65	3.2	V
		$T_j = 175\text{ °C}$	1.35	-	-	V
		$T_j = -55\text{ °C}$	-	-	3.65	V
$I_{DSS}$	drain leakage current	$V_{DS} = 25\ \text{V}; V_{GS} = 0\ \text{V}$				
		$T_j = 25\text{ °C}$	-	-	10	$\mu\text{A}$
		$T_j = 175\text{ °C}$	-	-	500	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = \pm 20\ \text{V}; V_{DS} = 0\ \text{V}$	-	-	100	nA
$R_G$	gate resistance	$f = 1\ \text{MHz}$	-	1.2	-	$\Omega$
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}; I_D = 25\ \text{A}$ ; see <a href="#">Figure 6</a> and <a href="#">8</a>				
		$T_j = 25\text{ °C}$	-	8.3	9.5	m $\Omega$
		$T_j = 175\text{ °C}$	-	15	17.1	m $\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 25\ \text{A}; V_{DS} = 12\ \text{V}; V_{GS} = 10\ \text{V}$ ; see <a href="#">Figure 11</a> and <a href="#">12</a>	-	17.1	-	nC
$Q_{GS}$	gate-source charge		-	6	-	nC
$Q_{GS1}$	pre- $V_{GS(th)}$ gate-source charge		-	3.2	-	nC
$Q_{GS2}$	post- $V_{GS(th)}$ gate-source charge		-	2.8	-	nC
$Q_{GD}$	gate-drain charge		-	3.2	-	nC
$V_{GS(pl)}$	gate-source plateau voltage		-	5	-	V
$Q_{G(tot)}$	total gate charge	$I_D = 0\ \text{A}; V_{DS} = 0\ \text{V}; V_{GS} = 4.5\ \text{V}$	-	6.2	-	nC
$C_{iss}$	input capacitance	$V_{GS} = 0\ \text{V}; V_{DS} = 12\ \text{V}; f = 1\ \text{MHz}$ ; see <a href="#">Figure 14</a>	-	860	-	pF
$C_{oss}$	output capacitance		-	400	-	pF
$C_{riss}$	reverse transfer capacitance		-	165	-	pF
$C_{iss}$	input capacitance	$V_{GS} = 0\ \text{V}; V_{DS} = 0\ \text{V}; f = 1\ \text{MHz}$	-	1200	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 12\ \text{V}; R_L = 0.5\ \Omega; V_{GS} = 10\ \text{V}$ ; $R_G = 5.6\ \Omega$	-	8.3	-	ns
$t_r$	rise time		-	7.6	-	ns
$t_{d(off)}$	turn-off delay time		-	24.8	-	ns
$t_f$	fall time		-	6.6	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 25\ \text{A}; V_{GS} = 0\ \text{V}$ ; see <a href="#">Figure 13</a>	-	0.9	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 20\ \text{A}; dI_S/dt = -100\ \text{A}/\mu\text{s}; V_{GS} = 0\ \text{V}$	-	34	-	ns
$Q_r$	recovered charge		-	12.5	-	nC



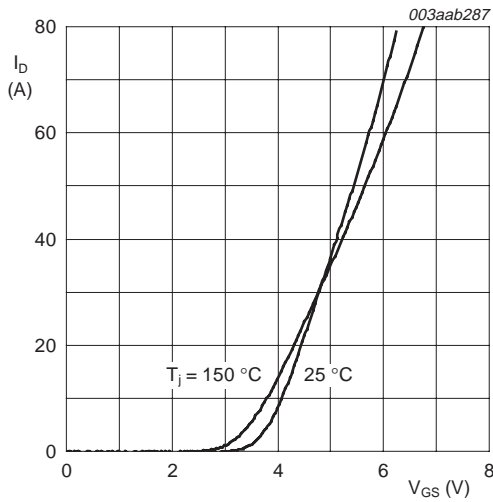
$T_j = 25\text{ }^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



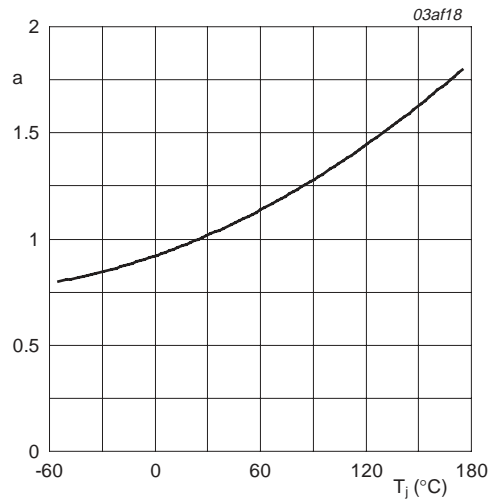
$T_j = 25\text{ }^\circ\text{C}$

Fig 6. Drain-source on-state resistance as a function of drain current; typical values



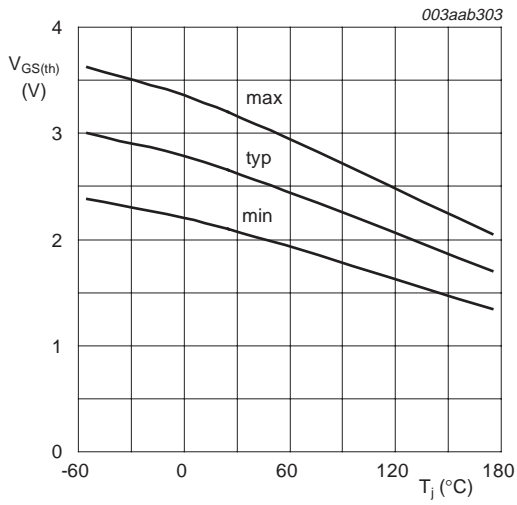
$T_j = 25\text{ }^\circ\text{C}$  and  $175\text{ }^\circ\text{C}$ ;  $V_{DS} > I_D \times R_{DS(on)}$

Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values



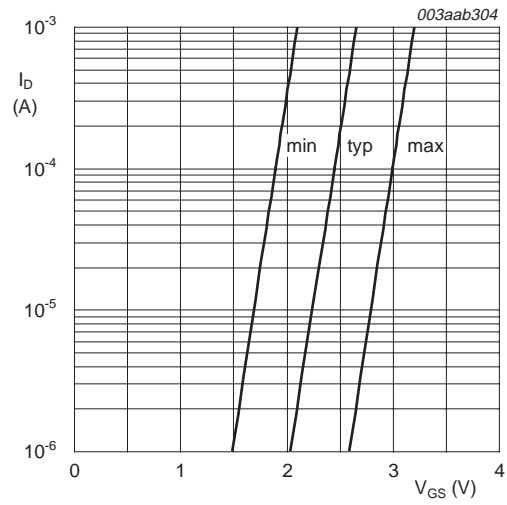
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature



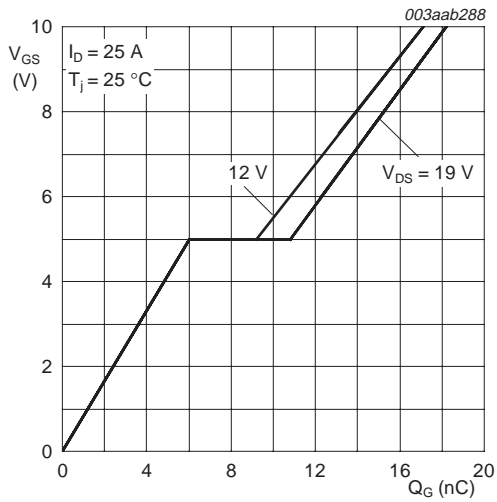
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature



$T_j = 25 \text{ }^{\circ}C; V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage



$I_D = 25 \text{ A}; V_{DS} = 12 \text{ V and } 19 \text{ V}$

Fig 11. Gate-source voltage as a function of gate charge; typical values

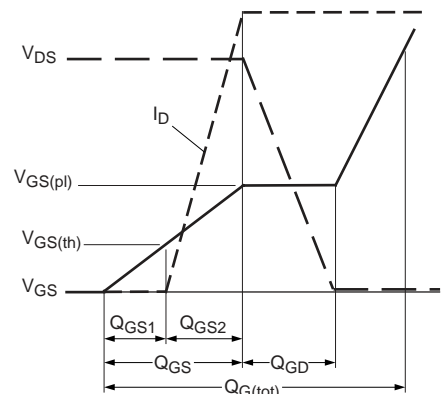
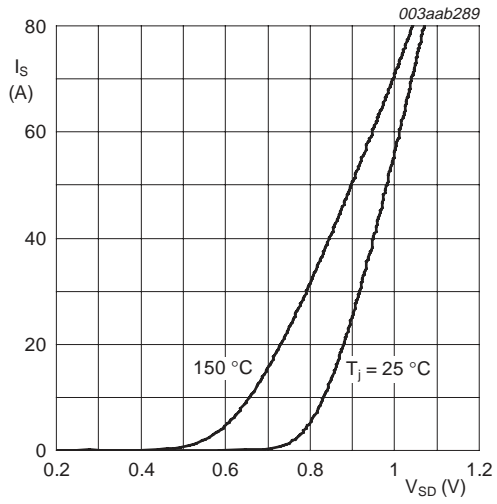
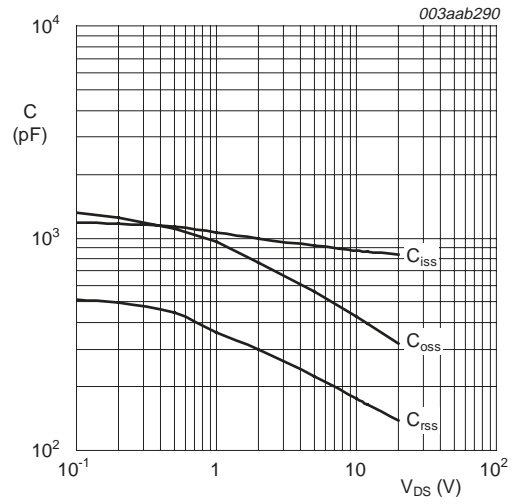


Fig 12. Gate charge waveform definitions



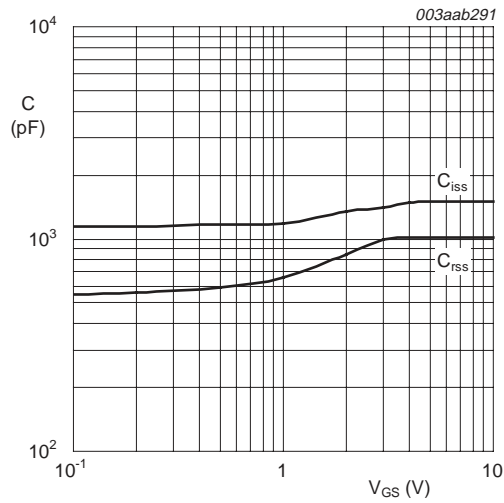
$T_j = 25\text{ }^\circ\text{C}$  and  $175\text{ }^\circ\text{C}$ ;  $V_{GS} = 0\text{ V}$

**Fig 13. Source current as a function of source-drain voltage; typical values**



$V_{GS} = 0\text{ V}$ ;  $f = 1\text{ MHz}$

**Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**



$V_{GS} = 0\text{ V}$ ;  $f = 1\text{ MHz}$

**Fig 15. Input and reverse transfer capacitances as a function of gate-source voltage; typical values**



7. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

SOT428

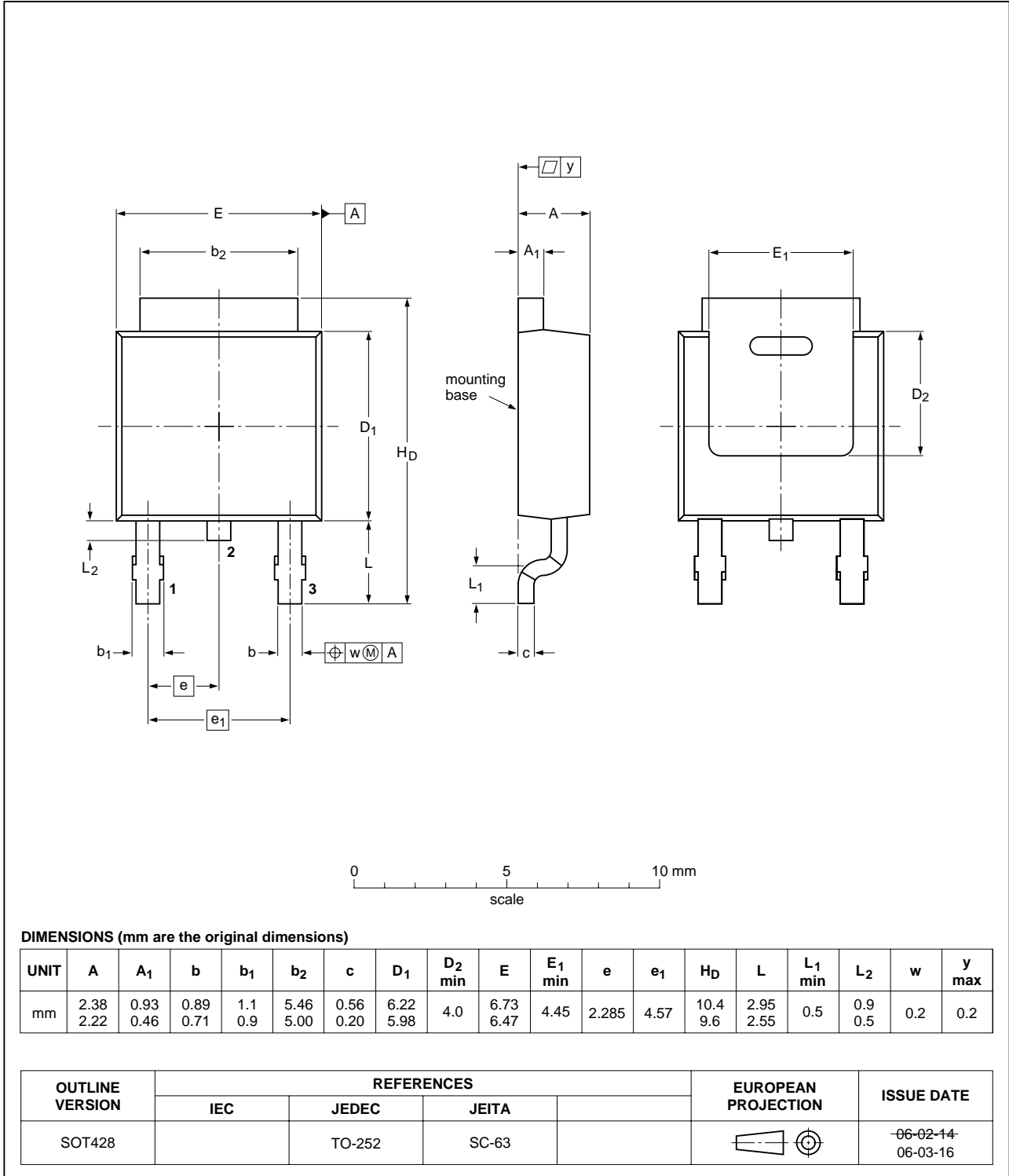
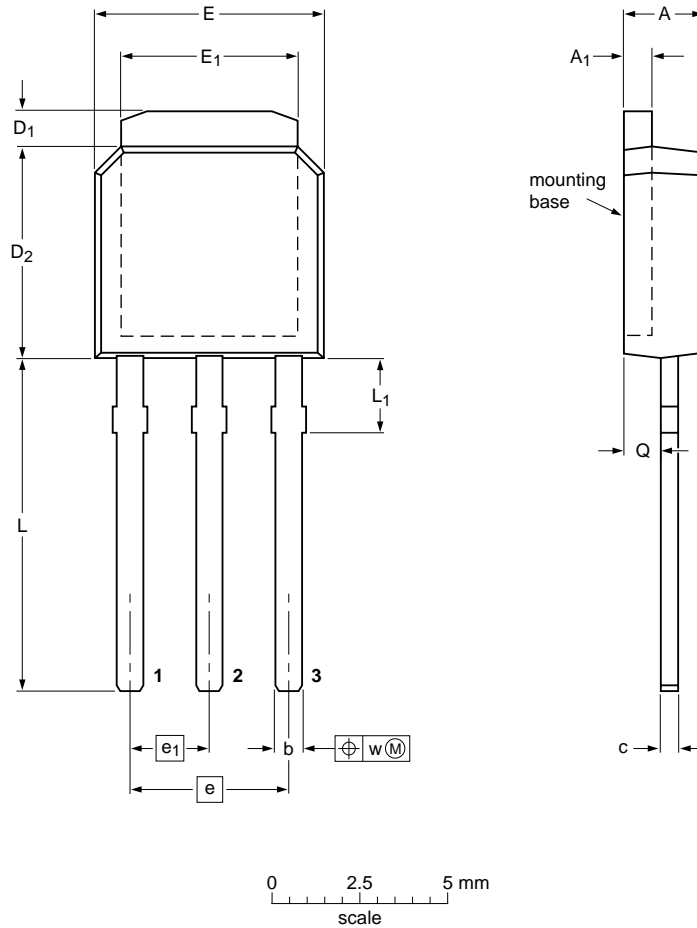


Fig 16. Package outline SOT428 (DPAK)

Plastic single-ended package (IPAK); 3 leads (in-line)

SOT533



**DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	c	D <sub>1</sub>	D <sub>2</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	L	L <sub>1</sub> <sup>(2)</sup> max	Q	w
mm	2.38 2.22	0.93 0.46	0.89 0.71	0.56 0.46	1.10 0.96	6.22 5.98	6.73 6.47	5.21 5.00	4.57 BSC <sup>(1)</sup>	2.285 BSC <sup>(1)</sup>	9.6 9.2	2.7	1.1 1.0	0.3

**Notes**

1. Basic spacing between centers.
2. Terminal dimensions are uncontrolled within zone L<sub>1</sub>.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT533		TO-251				-05-02-11- 06-02-14

Fig 17. Package outline SOT533 (IPAK)

## 8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PHD_PHU77NQ03T_1	20061128	Product data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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